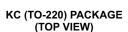


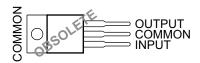
FIXED POSITIVE VOLTAGE REGULATORS

Check for Samples: µA7800 SERIES

FEATURES

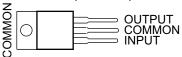
- 3-Terminal Regulators
- Available in fixed 5V/8V/10V/12V/15V/24V options
- Output Current up to 1.5 A



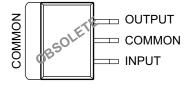


- Internal Thermal-Overload Protection
- High Power-Dissipation Capability
- Internal Short-Circuit Current Limiting
- Output Transistor Safe-Area Compensation

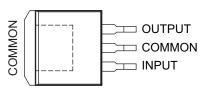




KTE (PowerFLEX™) PACKAGE (TOP VIEW)



KTT (TO-263) PACKAGE (TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 1.5 A of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents, and also can be used as the power-pass element in precision regulators.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



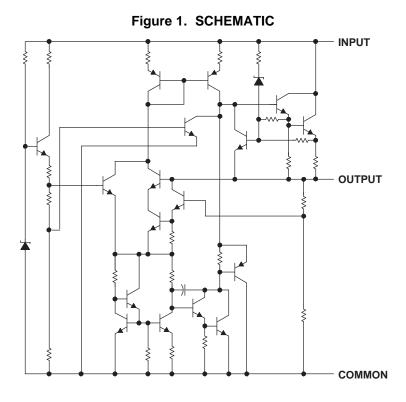
ORDERING INFORMATION(1)

TJ	V _{O(NOM)}	PACKAGE ⁽²)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		TO-220, short shoulder – KCS	Tube of 50	UA7805CKCS	UA7805C
		TO-220, single gauge – KCT	Tube of 50	UA7805CKCT	UA7805C
	5 V	TO-263 – KTT	Reel of 500	UA7805CKTTR	UA7805C
		PowerFLEX™ – KTE		OBSOLETE	OBSOLETE
		TO-220 – KC		OBSOLETE	OBSOLETE
		TO-220, short shoulder – KCS	Tube of 50	UA7808CKCS	UA7808C
		TO-220, single gauge – KCT	Tube of 50	UA7808CKCT	PREVIEW
	8 V	TO-263 – KTT	Reel of 500	UA7808CKTTR	UA7808C
		PowerFLEX – KTE		OBSOLETE	OBSOLETE
		TO-220 – KC		OBSOLETE	OBSOLETE
		TO-220, short shoulder – KCS	Tube of 50	UA7810CKCS	UA7810C
	40.1/	TO-263 – KTT	Reel of 500	UA7810CKTTR	UA7810C
	10 V	PowerFLEX – KTE		OBSOLETE	OBSOLETE
000 1- 40500		TO-220 – KC		OBSOLETE	OBSOLETE
0°C to 125°C		TO-220, short shoulder – KCS	Tube of 50	UA7812CKCS	UA7812C
		TO-220, single gauge – KCT	Tube of 50	UA7812CKCT	UA7812C
	12 V	TO-263 – KTT	Reel of 500	UA7812CKTTR	UA7812C
		PowerFLEX – KTE		OBSOLETE	OBSOLETE
		TO-220 – KC		OBSOLETE	OBSOLETE
		TO-220, short shoulder – KCS	Tube of 50	UA7815CKCS	UA7815C
		TO-220, single gauge – KCT	Tube of 50	UA7815CKCT	PREVIEW
	15 V	TO-263 – KTT	Reel of 500	UA7815CKTTR	UA7815C
		PowerFLEX – KTE		OBSOLETE	OBSOLETE
		TO-220 – KC		OBSOLETE	OBSOLETE
		TO-220, short shoulder – KCS	Tube of 50	UA7824CKCS	UA7824C
	24.1/	TO-263 – KTT	Reel of 500	UA7824CKTTR	UA7824C
	24 V	PowerFLEX – KTE		OBSOLETE	OBSOLETE
		TO-220 – KC		OBSOLETE	OBSOLETE

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

⁽²⁾ Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.





Absolute Maximum Ratings(1)

over virtual junction temperature range (unless otherwise noted)

			MIN	MAX	UNIT
VI	lonut voltogo	μA7824C		40	V
VI	Input voltage	All others		35	V
T_{J}	Operating virtual junction temperature	•		150	°C
	Lead temperature	1,6 mm (1/16 in) from case for 10 s		260	°C
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Package Thermal Data(1)

PACKAGE	BOARD	θ_{JA}	θ _{JC}	θ _{JP} ⁽²⁾
PowerFLEX (KTE) – OBSOLETE	High K, JESD 51-5	23°C/W	3°C/W	2.7°C/W
TO-220 (KCS), (KCT) (KC – OBSOLETE)	High K, JESD 51-5	19°C/W	17°C/W	3°C/W
TO-263 (KTT)	High K, JESD 51-5	25.3°C/W	18°C/W	1.94°C/W

Maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability. For packages with exposed thermal pads, such as QFN, PowerPADTM, or PowerFLEX, θ_{JP} is defined as the thermal resistance between the die junction and the bottom of the exposed pad.



Recommended Operating Conditions

			MIN	MAX	UNIT	
		μΑ7805	7	25		
		μΑ7808	10.5	25		
V. Input voltage	μA7810	12.5	28	.,		
VI	input voitage	μA7812	14.5	30	V	
	Input voltage		μA7815	17.5	30	
		μΑ7824	27	38		
Io	Output current	1		1.5	Α	
T_{J}	Operating virtual junction temperature		0	125	°C	



uA7805 Electrical Characteristics

at specified virtual junction temperature, V_I = 10 V, I_O = 500 mA (unless otherwise noted)

DADAMETED	TEST COMPITIONS	T (1)	μ	A7805C		LINUT
PARAMETER	TEST CONDITIONS	T _J (1) 25°C 4.8 0°C to 125°C 4.75 25°C 0°C to 125°C 62 25°C 0°C to 125°C 25°C 25°C	TYP	MAX	UNIT	
Output voltage	$I_0 = 5 \text{ mA to } 1 \text{ A}, V_1 = 7 \text{ V to } 20 \text{ V},$	25°C	4.8	5	5.2	V
Output voltage	P _D ≤ 15 W	0°C to 125°C	4.75		5.25	V
land colland and collection	V _I = 7 V to 25 V	25.0		3	100	\/
Input voltage regulation	V _I = 8 V to 12 V	25°C		1	50	mV
Ripple rejection ⁽²⁾	V _I = 8 V to 12 V, f = 120 Hz	0°C to 125°C	62	78		dB
Rippie rejection—	V _I = 8 V to 12 V, f = 120 Hz (KCT)	0.0 10 125.0		68		uБ
Outroit valta as a solution	I _O = 5 mA to 1.5 A	25.0		15	100	\/
Output voltage regulation	I _O = 250 mA to 750 mA	25°C		5	50	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.017		Ω
Temperature coefficient of output voltage	I _O = 5 mA	0°C to 125°C		-1.1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		40		μV
Dropout voltage	I _O = 1 A	25°C		2		V
Bias current		25°C		4.2	8	mA
Dies surrent change	V _I = 7 V to 25 V	0°C to 105°C			1.3	A
Bias current change	I _O = 5 mA to 1 A	0.0 10.125.0			0.5	mA
Short-circuit output current		25°C		750		mA
Peak output current		25°C		2.2		Α

Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.

uA7808 Electrical Characteristics

at specified virtual junction temperature, V_I = 14 V, I_O = 500 mA (unless otherwise noted)

DADAMETER	TEST COMPITIONS	T (1)	μΑ7808C			LINUT
PARAMETER	TEST CONDITIONS	1, \''	MIN 25°C 7.7 to 125°C 7.6 25°C to 125°C 55 25°C to 125°C 25°C 25°C 25°C 25°C 25°C 25°C 25°C	TYP	MAX	UNIT
Output valta as	$I_0 = 5 \text{ mA to } 1 \text{ A}, V_1 = 10.5 \text{ V to } 23 \text{ V},$	25°C	7.7	8	8.3	V
Output voltage	P _D ≤ 15 W	0°C to 125°C	7.6		8.4	V
Input valtage regulation	V _I = 10.5 V to 25 V	25°C		6	160	mV
Input voltage regulation	V _I = 11 V to 17 V	25 0		2	80	IIIV
Ripple rejection (2)	V _I = 11.5 V to 21.5 V, f = 120 Hz	0°C to 125°C	55	72		dB
Output valtage regulation	I _O = 5 mA to 1.5 A	25°C		12	160	m\/
Output voltage regulation	I _O = 250 mA to 750 mA	25 0		4	80	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.016		Ω
Temperature coefficient of output voltage	$I_O = 5 \text{ mA}$	0°C to 125°C		-0.8		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		52		μV
Dropout voltage	I _O = 1 A	25°C		2		V
Bias current		25°C		4.3	8	mA
Pigg gurrent change	$V_{I} = 10.5 \text{ V to } 25 \text{ V}$	0°C to 125°C			1	mA
Bias current change	$I_O = 5$ mA to 1 A	0 C to 125 C			0.5	IIIA
Short-circuit output current		25°C		450		mA
Peak output current		25°C		2.2		Α

⁽¹⁾ Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.

⁽²⁾ This parameter is validated by design and verified during product characterization. It is not tested in production.

⁽²⁾ This parameter is validated by design and verified during product characterization. It is not tested in production.



uA7810 Electrical Characteristics

at specified virtual junction temperature, $V_1 = 17 \text{ V}$, $I_0 = 500 \text{ mA}$ (unless otherwise noted)

DARAMETER	TEST COMPLETIONS	T _J ⁽¹⁾	μ	A7810C		
PARAMETER	TEST CONDITIONS	1, ('')	MIN	TYP	MAX	UNIT
Output voltage	$I_O = 5$ mA to 1 A, $V_I = 12.5$ V to 25 V,	25°C	9.6	10	10.4	V
Output voltage	P _D ≤ 15 W	0°C to 125°C	9.5		10.5	V
Input valtage regulation	V _I = 12.5 V to 28 V	25°C		7	200	m)/
Input voltage regulation	V _I = 14 V to 20 V	25 C		2	100	mV
Ripple rejection (2)	V _I = 13 V to 23 V, f = 120 Hz	0°C to 125°C	55	71		dB
Output voltage regulation	I _O = 5 mA to 1.5 A	25°C		12	200	mV
Output voltage regulation	I _O = 250 mA to 750 mA	25 C		4	100	IIIV
Output resistance	f = 1 kHz	0°C to 125°C		0.018		Ω
Temperature coefficient of output voltage	$I_O = 5 \text{ mA}$	0°C to 125°C		-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		70		μV
Dropout voltage	I _O = 1 A	25°C		2		V
Bias current		25°C		4.3	8	mA
Pigg current change	V _I = 12.5 V to 28 V	0°C to 125°C			1	mΛ
Bias current change	$I_O = 5 \text{ mA to } 1 \text{ A}$	0 C to 125 C			0.5	mA
Short-circuit output current		25°C		400		mA
Peak output current		25°C		2.2		Α

⁽¹⁾ Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.

uA7812 Electrical Characteristics

at specified virtual junction temperature, $V_1 = 19 \text{ V}$, $I_0 = 500 \text{ mA}$ (unless otherwise noted)

DADAMETED	TEST COMPLETIONS	T,, (1)	μ	A7812C		UNIT
PARAMETER	TEST CONDITIONS	IJ (''	MIN	TYP	MAX	UNIT
Output valta as	$I_0 = 5 \text{ mA to 1 A}, V_1 = 14.5 \text{ V to 27 V},$	25°C	11.5	12	12.5	V
Output voltage	P _D ≤ 15 W	0°C to 125°C	11.4		12.6	V
land to alternate and addition	V _I = 14.5 V to 30 V	0500		10	240	\/
Input voltage regulation	V _I = 16 V to 22 V	25°C		3	120	mV
Diamin sain sting (2)	V _I = 15 V to 25 V, f = 120 Hz	0°C to 125°C	55	71		٩D
Ripple rejection (2)	V _I = 15 V to 25 V, f = 120 Hz (KCT)	0°C to 125°C		61		dB
Output walks as a search of a	I _O = 5 mA to 1.5 A	0500		12	240	
Output voltage regulation	I _O = 250 mA to 750 mA	25°C		4	120	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.018		Ω
Temperature coefficient of output voltage	I _O = 5 mA	0°C to 125°C		-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		75		μV
Dropout voltage	I _O = 1 A	25°C		2		V
Bias current		25°C		4.3	8	mA
Dies summer shares	V _I = 14.5 V to 30 V	000 +- 40500			1	A
Bias current change	I _O = 5 mA to 1 A	0°C to 125°C			0.5	mA
Short-circuit output current		25°C		350		mA
Peak output current		25°C		2.2		Α

⁽¹⁾ Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.

⁽²⁾ This parameter is validated by design and verified during product characterization. It is not tested in production.

⁽²⁾ This parameter is validated by design and verified during product characterization. It is not tested in production.



uA7815 Electrical Characteristics

at specified virtual junction temperature, V_I = 23 V, I_O = 500 mA (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T (1)	μ	A7815C		LINUT
PARAMETER	TEST CONDITIONS	T _J ⁽¹⁾	MIN	TYP	MAX	UNIT
Output valtage	$I_{O} = 5 \text{ mA to 1 A}, V_{I} = 17.5 \text{ V to 30 V},$	25°C	14.4	15	15.6	V
Output voltage	P _D ≤ 15 W	0°C to 125°C	14.25		15.75	V
land delication	V _I = 17.5 V to 30 V	25.0		11	300	\/
Input voltage regulation	V _I = 20 V to 26 V	25°C		3	150	mV
Ripple rejection (2)	V _I = 18.5 V to 28.5 V, f = 120 Hz	0°C to 125°C	54	70		dB
Output voltage regulation	I _O = 5 mA to 1.5 A	25°C		12	300	m)/
Output voltage regulation	I _O = 250 mA to 750 mA	25°C		4	150	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.019		Ω
Temperature coefficient of output voltage	I _O = 5 mA	0°C to 125°C		-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		90		μV
Dropout voltage	I _O = 1 A	25°C		2		V
Bias current		25°C		4.4	8	mA
Diag assessed all agents	V _I = 17.5 V to 30 V	000 +- 40500			1	A
Bias current change	I _O = 5 mA to 1 A	0°C to 125°C			0.5	mA
Short-circuit output current		25°C		230		mA
Peak output current		25°C		2.1		Α

⁽¹⁾ Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

uA7824 Electrical Characteristics

at specified virtual junction temperature, $V_1 = 33 \text{ V}$, $I_0 = 500 \text{ mA}$ (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T (1)	μA7824C			LINUT
PARAMETER	TEST CONDITIONS	T _J ⁽¹⁾	MIN	TYP	MAX	UNIT
Output valta as	$I_0 = 5 \text{ mA to } 1 \text{ A}, V_1 = 27 \text{ V to } 38 \text{ V},$	25°C	23	24	25	V
Output voltage	P _D ≤ 15 W	0°C to 125°C	22.8		25.2	V
lanut valtage regulation	V _I = 27 V to 38 V	25°C		18	480	m)/
Input voltage regulation	V _I = 30 V to 36 V	25 C		6	240	mV
Ripple rejection (2)	V _I = 28 V to 38 V, f = 120 Hz	0°C to 125°C	50	66		dB
Output valta as assulation	I _O = 5 mA to 1.5 A	2500		12	480	\/
Output voltage regulation	I _O = 250 mA to 750 mA	25°C		4	240	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.028		Ω
Temperature coefficient of output voltage	I _O = 5 mA	0°C to 125°C		-1.5		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		170		μV
Dropout voltage	I _O = 1 A	25°C		2		V
Bias current		25°C		4.6	8	mA
Diag ourrent change	V _I = 27 V to 38 V	0°C to 125°C			1	A
Bias current change	I _O = 5 mA to 1 A	0°C to 125°C			0.5	mA
Short-circuit output current		25°C		150		mA
Peak output current		25°C		2.1		Α

⁽¹⁾ Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

⁽²⁾ This parameter is validated by design and verified during product characterization. It is not tested in production.

⁽²⁾ This parameter is validated by design and verified during product characterization. It is not tested in production.



APPLICATION INFORMATION

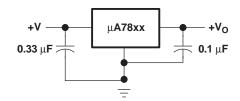


Figure 2. Fixed-Output Regulator

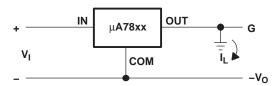
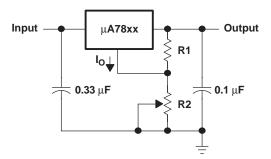


Figure 3. Positive Regulator in Negative Configuration (V_I Must Float)



A: The following formula is used when V_{xx} is the nominal output voltage (output to common) of the fixed regulator:

$$V_{O} = V_{xx} + \left(\frac{V_{xx}}{R1} + I_{Q}\right)R2$$

Figure 4. Adjustable-Output Regulator

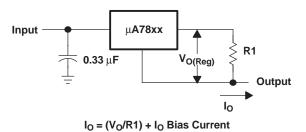


Figure 5. Current Regulator



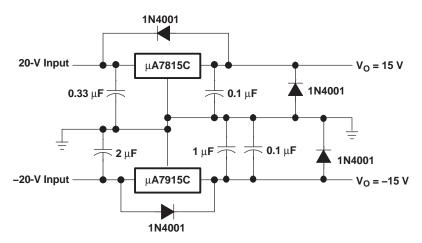


Figure 6. Regulated Dual Supply

Operation With a Load Common to a Voltage of Opposite Polarity

In many cases, a regulator powers a load that is not connected to ground but, instead, is connected to a voltage source of opposite polarity (e.g., operational amplifiers, level-shifting circuits, etc.). In these cases, a clamp diode should be connected to the regulator output as shown in Figure 7. This protects the regulator from output polarity reversals during startup and short-circuit operation.

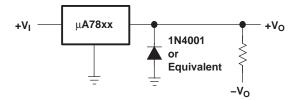


Figure 7. Output Polarity-Reversal-Protection Circuit

Reverse-Bias Protection

Occasionally, the input voltage to the regulator can collapse faster than the output voltage. This can occur, for example, when the input supply is crowbarred during an output overvoltage condition. If the output voltage is greater than approximately 7 V, the emitter-base junction of the series-pass element (internal or external) could break down and be damaged. To prevent this, a diode shunt can be used as shown in Figure 8.

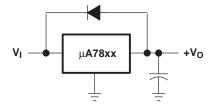


Figure 8. Reverse-Bias-Protection Circuit

SLVS056N -MAY 1976-REVISED JUNE 2012



REVISION HISTORY

Cł	hanges from Revision M (January 2009) to Revision N	Page
•	Added KCT package and orderable part number to the ORDERING INFORMATION table.	2

26-Jun-2012

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
UA7805CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	
UA7805CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	
UA7805CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	
UA7805CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	
UA7805CKCT	ACTIVE	TO-220	KCT	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	
UA7805CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	
UA7805CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	
UA7805CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	
UA7805QKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	
UA7805QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	
UA7808CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	
UA7808CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	
UA7808CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	
UA7808CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	
UA7808CKCT	PREVIEW	TO-220	KCT	3	50	TBD	Call TI	Call TI	
UA7808CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	
UA7808CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	
UA7808CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	
UA7808QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	
UA7810CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	
UA7810CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI	
UA7810CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	
UA7810CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	
UA7810CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	
UA7810CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	



www.ti.com 26-Jun-2012

Orderable Device	erable Device _{Status} ⁽¹⁾ Package Type Package Pins Package Qty Eco Plan ⁽ Drawing		Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)				
UA7810CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR		
UA7810QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI		
UA7812CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI		
UA7812CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI		
UA7812CKCS	ACTIVE	TO-220	KCS	3	50 Pb-Free (RoHS)		CU SN	N / A for Pkg Type		
UA7812CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type		
UA7812CKCT	ACTIVE	TO-220	KCT	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type		
UA7812CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI		
UA7812CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR		
UA7812CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)				
UA7812QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI		
UA7815CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI		
UA7815CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type		
UA7815CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type		
UA7815CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI		
UA7815CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR		
UA7815CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR		
UA7815QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI		
UA7824CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI		
UA7824CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI		
UA7824CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type		
UA7824CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type		
UA7824CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI		
UA7824CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR		
UA7824CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	•			
UA7885CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI		



PACKAGE OPTION ADDENDUM

26-Jun-2012

Orderable Device	Status (1) P	ackage Typ	e Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
UA7885CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	
UA7885QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

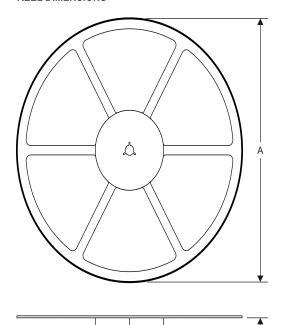
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

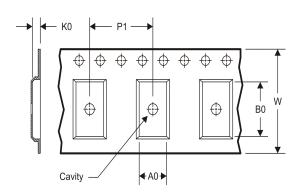
www.ti.com 19-Jun-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

"All dimensions are nomina	1	1			1							_
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA7805CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
UA7808CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
UA7810CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
UA7812CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
UA7815CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
UA7824CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2

www.ti.com 19-Jun-2012

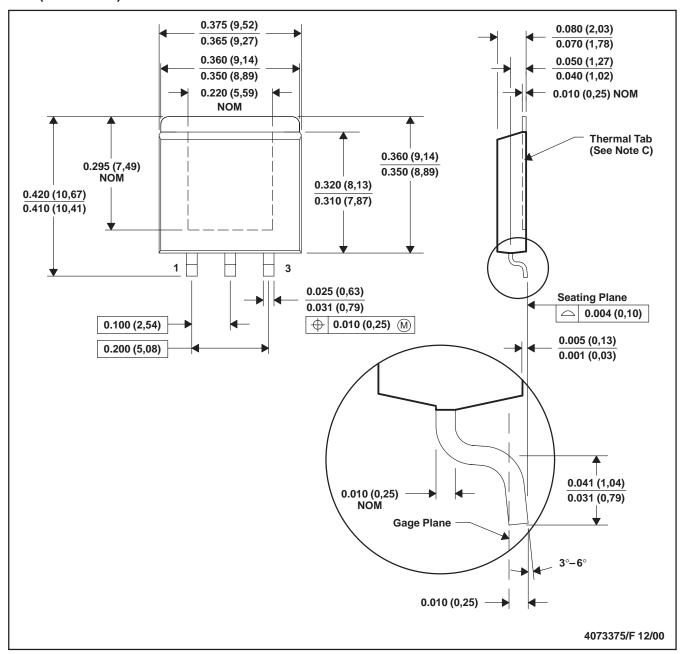


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA7805CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7808CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7810CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7812CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7815CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7824CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0

KTE (R-PSFM-G3)

PowerFLEX™ PLASTIC FLANGE-MOUNT



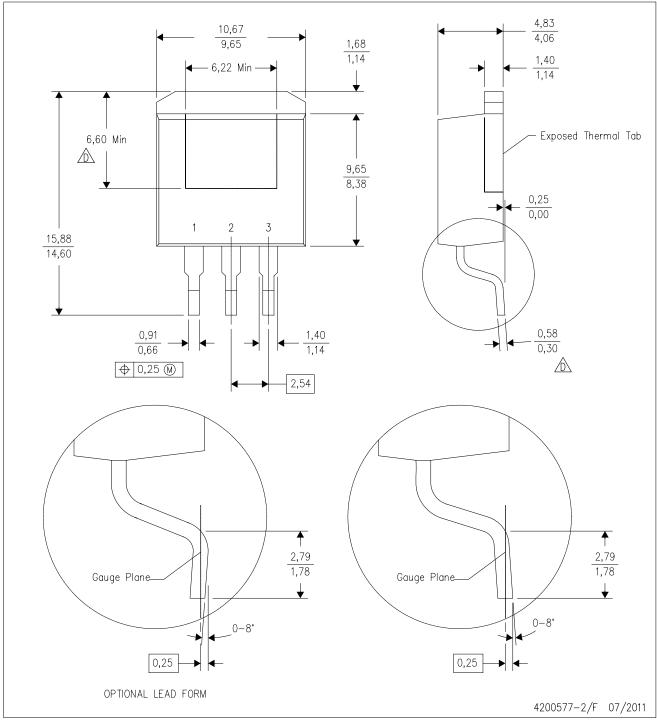
- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. The center lead is in electrical contact with the thermal tab.
 - D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
 - E. Falls within JEDEC MO-169

PowerFLEX is a trademark of Texas Instruments.



KTT (R-PSFM-G3)

PLASTIC FLANGE-MOUNT PACKAGE

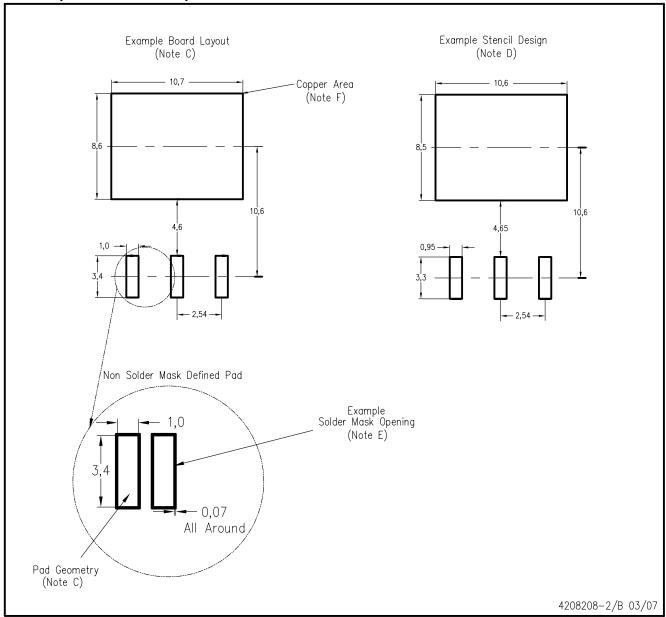


NOTES:

- A. All linear dimensions are in millimeters.
- 3. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
- Falls within JEDEC T0—263 variation AA, except minimum lead thickness and minimum exposed pad length.



KTT (R-PSFM-G3)



NOTES: A. All linear dimensions are in millimeters.

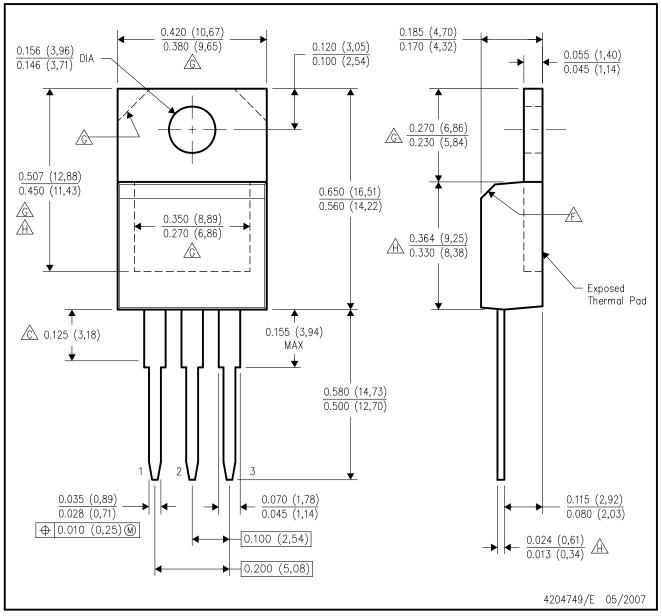
- B. This drawing is subject to change without notice.
- C. Publication IPC-SM-782 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release.

 Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
- F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.



KCS (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



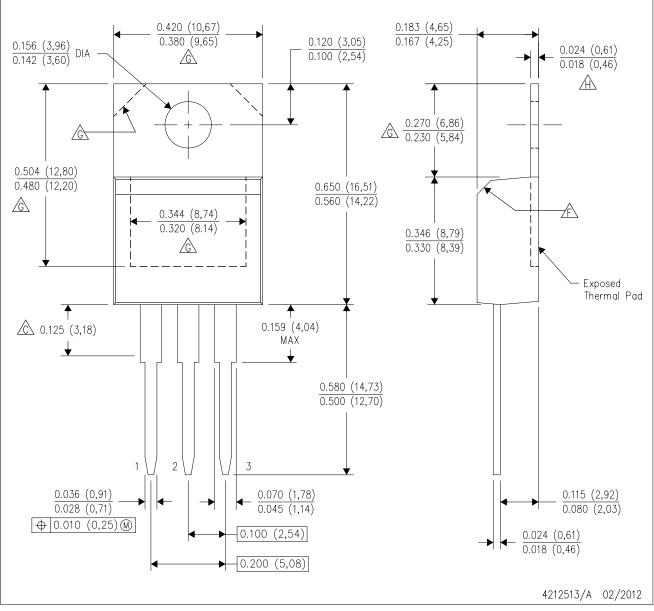
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC T0—220 variation AB, except minimum lead thickness, minimum exposed pad length, and maximum body length.



KCT (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



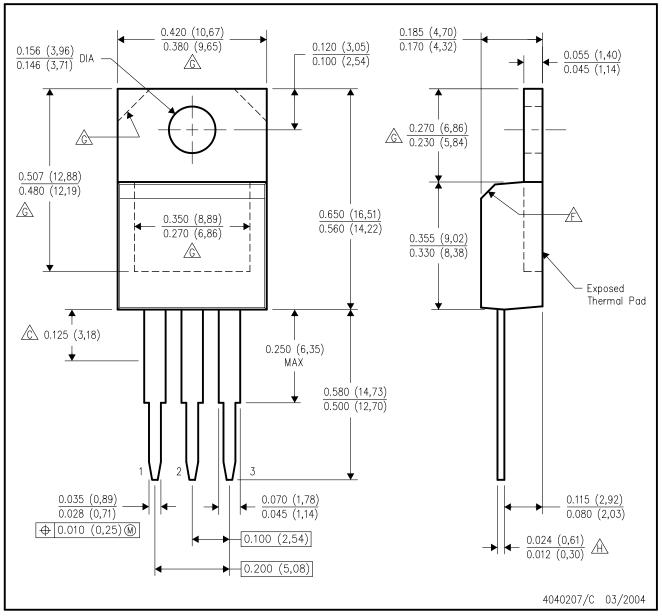
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-220 variation AB, except minimum tab thickness.



KC (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-220 variation AB, except minimum lead thickness.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

Applications

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Wireless Connectivity

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications dataconverter.ti.com Computers and Peripherals www.ti.com/computers **Data Converters DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic logic.ti.com Security www.ti.com/security Power Mgmt www.ti.com/space-avionics-defense power.ti.com Space, Avionics and Defense Microcontrollers Video and Imaging microcontroller.ti.com www.ti.com/video www.ti-rfid.com **OMAP Mobile Processors** www.ti.com/omap

TI E2E Community Home Page

www.ti.com/wirelessconnectivity

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2012, Texas Instruments Incorporated

e2e.ti.com